

1. (Amended) A fabricating method of a semiconductor package, comprising the steps of:
 - providing a substrate having a device-mounting region on a surface of the substrate, and a wire bonding region predefined around the device-mounting region for forming a plurality of bonding fingers thereon;
 - mounting a plurality of passive devices on the device-mounting region;
 - using an insulative material for encapsulating the passive devices;
 - disposing a semiconductor chip on a surface of the insulative material above the passive devices, such that the semiconductor chip is free of contact with the passive devices and the substrate;
 - providing a plurality of bonding wires for electrically connecting the semiconductor chip to the bonding fingers of the substrate;
 - forming an encapsulant for encapsulating the semiconductor chip and the bonding wires;and
 - providing a plurality of conductive members for electrically connecting the substrate to an external device.
11. (Amended) A semiconductor package, comprising:
 - a substrate having a device-mounting region predefined on a surface of the substrate, and a wire bonding region predefined around the device-mounting region for forming a plurality of bonding fingers thereon;
 - a plurality of passive devices attached to the device-mounting region;
 - an insulative material for encapsulating the passive devices;
 - a semiconductor chip disposed on a surface of the insulative material above the passive devices, such that the semiconductor chip is free of contact with the passive devices and the substrate;
 - a plurality of bonding wires for electrically connecting the semiconductor chip to the bonding fingers of the substrate;
 - an encapsulant for encapsulating the semiconductor chip and the bonding wires; and
 - a plurality of conductive members for electrically connecting the substrate to an external device.